



2018 Q3 Results Announcement

November 1, 2018



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ASMPT Recognized as TOP 100 Global Tech Leaders



“The Top 100 Global Technology Leaders are the organizations poised to propel the future of technology”,
Brian Scanlon, Chief Strategy Officer

Thomson Reuters, 2018

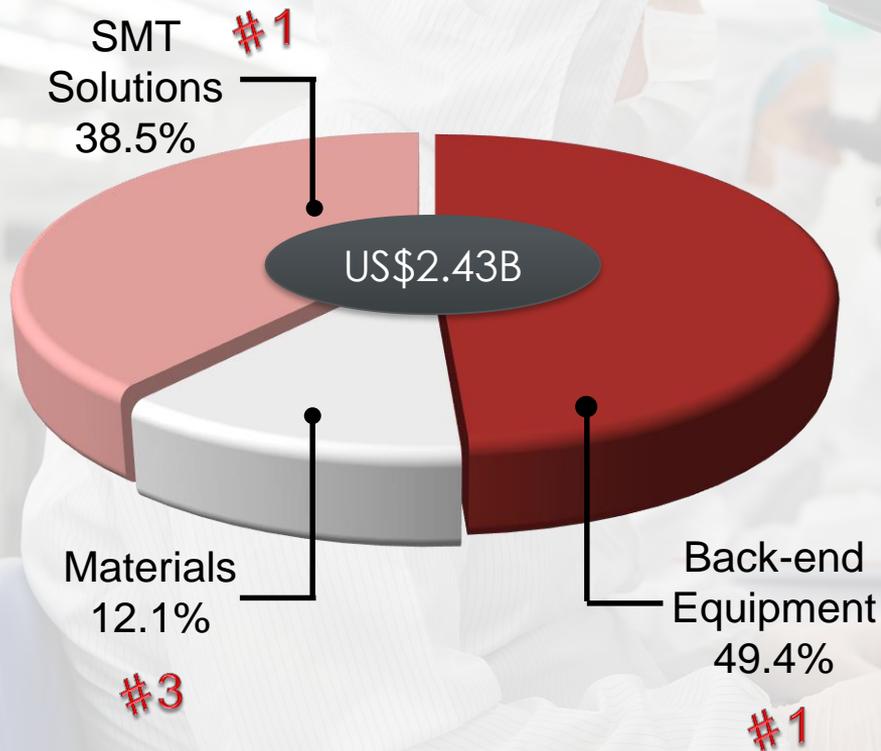
The **ONLY** Back-end Equipment Supplier Recognized

CORPORATE OVERVIEW



A World's Technology & Market Leader

Q3 2018 LTM Group Revenue
 (CAGR 2008-Q3 2018 LTM 13.7 %)



- A leading Integrated Solutions Provider in the semiconductor assembly and packaging industry as well as in the SMT solutions market
- A leading player for CIS, LED, and Automotive
- 3 high growth markets accounted for 48% of group revenue in first 9M 2018



ASMPT Global Presence



Added 4 R&D Centers this year in Taoyuan, Regensburg, Porto, and Boston

 <p>> 2,000 global R&D staff</p>	 <p>> 1,100 patents on key leading edge technologies</p>	 <p>10 R&D centers worldwide</p>	 <p>12 manufacturing facilities</p>
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ASMPT Major Facilities around the World

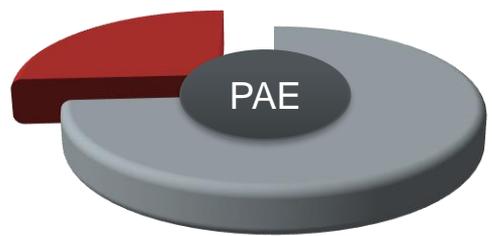


Three Business Segments With Leading Market Positions

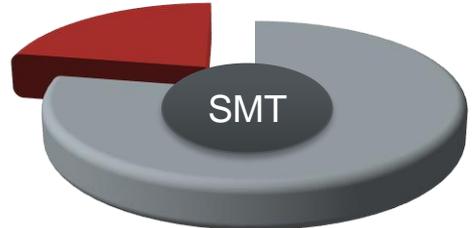
Worldwide Market Position & Share

Back-end Equipment **#1 Assembly & Packaging Equipment Market** **~25% (2017)**

- #1 Die Bonders
- #2 Wire Bonders
- #1/2 Flip Chip Bonders
- #1 Thermal Compression Bonders (TCB)
- #1 LED Packaging Equipment
- #1 CMOS Imaging Sensors (CIS) Equipment
- #2 Encapsulation & Post Encapsulation Solutions
- #4 Turret Test Equipment (Test Handlers)
- #2 Laser Dicing and Grooving



SMT Solutions **#1 SMT Equipment Market** **~22% (2017)**



Materials **#3 Leadframe Market** **~8.7% (2017)**



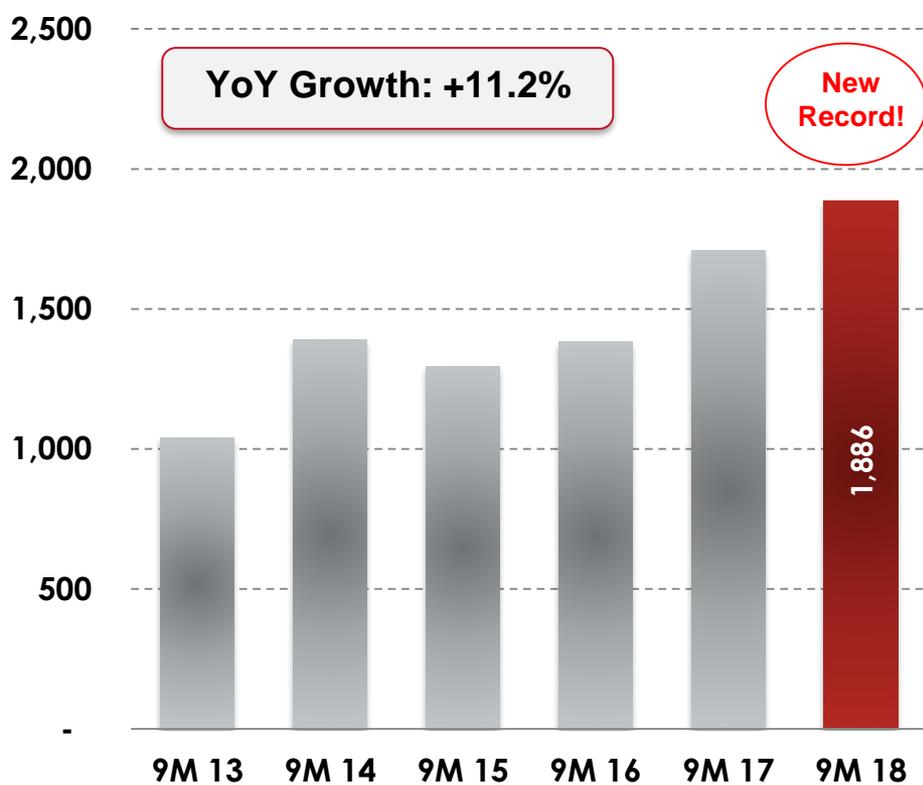
Sources:
 Market share for Back-end Equipment is based on information on packaging and assembly equipment market by VLSI, leadframe market by SEMI, and SMT market by ASMPT SIPLACE Market Intelligence

2018 Q3/9M Highlights

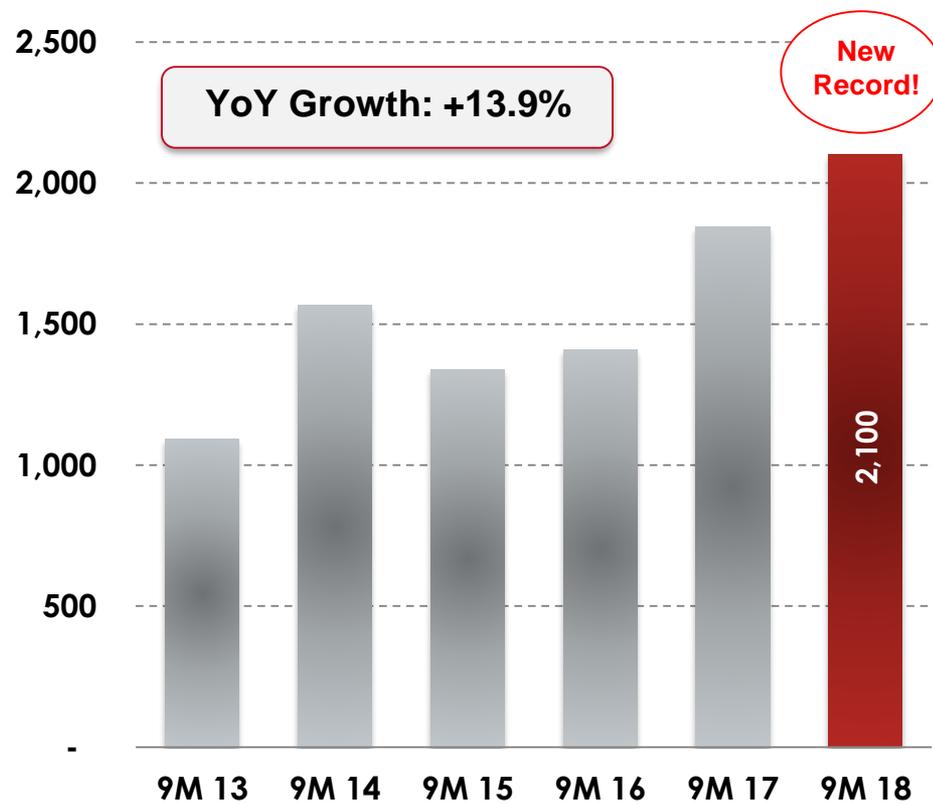


Record 9-Month Group Bookings & Billings

Billings (US\$ m)



Bookings (US\$ m)



Q3/9M 2018 Group Financial Highlights

	Q3 2018		9M 2018	
	Amount	YoY	Amount	YoY
Bookings (USD)	618.6m 	 7.7%	2.1b 	 13.9%
Billings (USD)	658.3m 	 1.1%	1.9b 	 11.2%
Gross Margin	37.8%	 283bps	39.7%	 88bps
EBIT (HKD)	818.8m	 25.3%	2.7b	 2.7% [^]
Net Profit (HKD)	602.1m	 30.2%	2.0b	 6.6% [^]
Net Profit Margin	11.7%	 523bps	13.5%	 257bps [^]

 **New Record**

 **Highest in Q3**

[^]Excludes adj. of liability component of CB

Strong Q3 Bookings led by SMT/Back-end Equipment

	Q3 Bookings		Q3 Billings	
	Amount (US\$m)	YoY	Amount (US\$m)	YoY
Group	618.6 	 7.7%	658.3 	 1.1%
Back-end Equipment	263.9	 5.8%	302.6 	 5.4%
Materials	53.9	 20.8%	76.9 	 4.1%
SMT Solutions	300.8 	 17.1%	278.8	 3.9%

 New Record

 Highest in Q3

Strong 9M 2018 Bookings/Billings

	First 9M Bookings		First 9M Billings	
	Amount (US\$m)	YoY	Amount (US\$m)	YoY
Group	2,100.5 [★]	↑ 13.9%	1,885.6 [★]	↑ 11.2%
Back-end Equipment	1,024.8	↑ 13.8%	947.9 [★]	↑ 11.4%
Materials	204.9	↓ 11.4%	227.9 [★]	↑ 9.2%
SMT Solutions	870.8 [★]	↑ 22.3%	709.8 [★]	↑ 11.6%

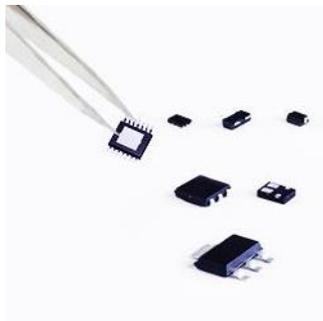
[★] New Record

Major Drivers for Q3 2018 Bookings/Billings

Back-end

IC / Discrete

Discrete Semiconductors



Automotive



Consumer



Power Management



Industrial

SMT Solutions



Industrial



Automotive



China Smartphones

9M 2018 Segments Highlights

9M 2018	Back-end Equipment Segment		Materials Segment		SMT Solutions Segment	
	9M 2018	YoY	9M 2018	YoY	9M 2018	YoY
Bookings (USD)	1,024.8m	↑ 13.8%	204.9m	↓ 11.4%	870.8m★	↑ 22.3%
Billings (USD)	947.9m★	↑ 11.4%	227.9m★	↑ 9.2%	709.8m★	↑ 11.6%
Gross Margin	46.6%	↓ 112bps	12.4%	↓ 152bps	39.2%	↓ 52bps
Segment Profit (HKD)	1,845.8m	↑ 5.7%	110.4m	↓ 8.6%	975.9m★	↑ 7.9%
Segment Profit Margin	24.8%	↓ 133bps	6.2%	↓ 121bps	17.5%	↓ 59bps

★ New Record

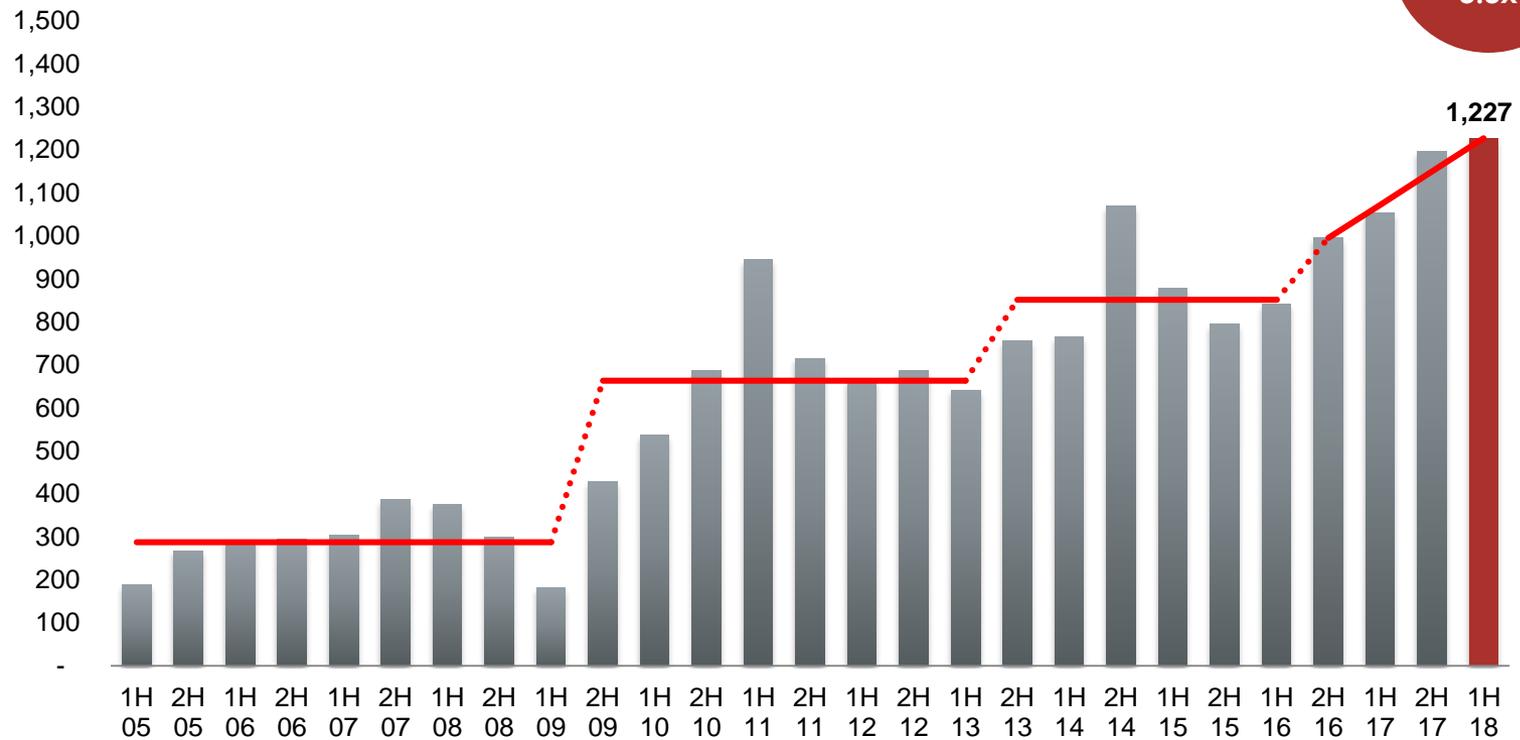
Impacts of Trade War – Insignificant So Far

- **Direct impact:** <0.5% of Group Billing
- **Indirect impact:**
 - Export oriented customers in China: getting more cautious
 - Domestic oriented customers in China: continue to expand
 - SEA customers: Increase orders to ASMPT
- **Prolonged trade war would increase market uncertainties**

ASMPT Has Entered a High Growth Period

Group Half Yearly Billings
(US\$ m)

1H18 Rev
vs 1H08
3.3x



OUTLOOK

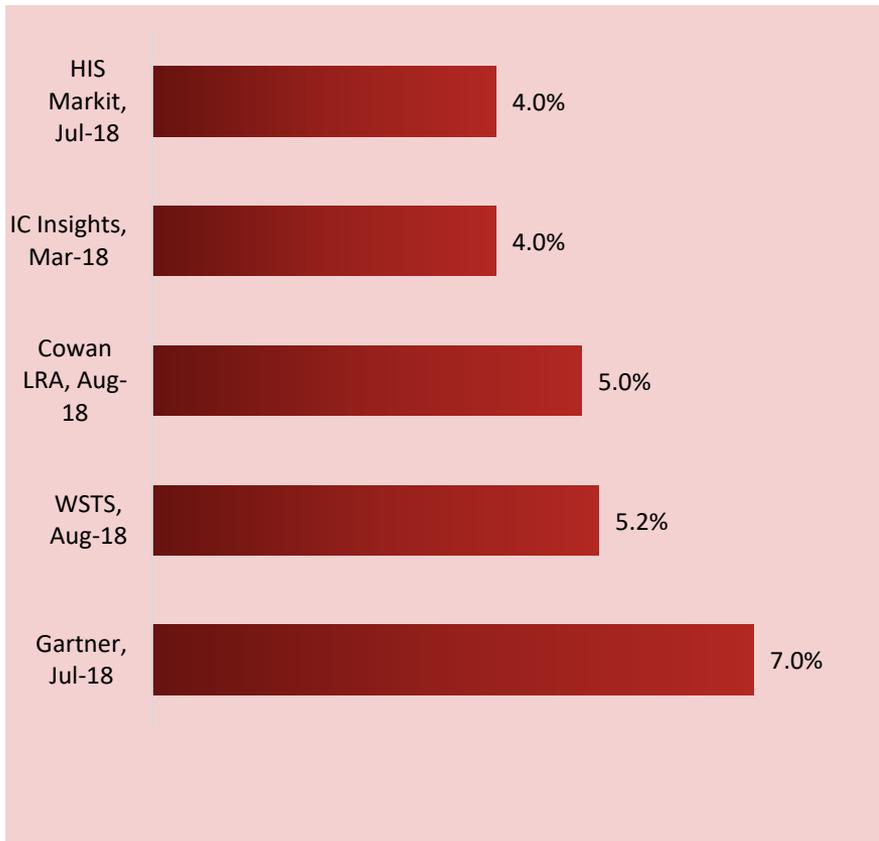


Outlook for Q4

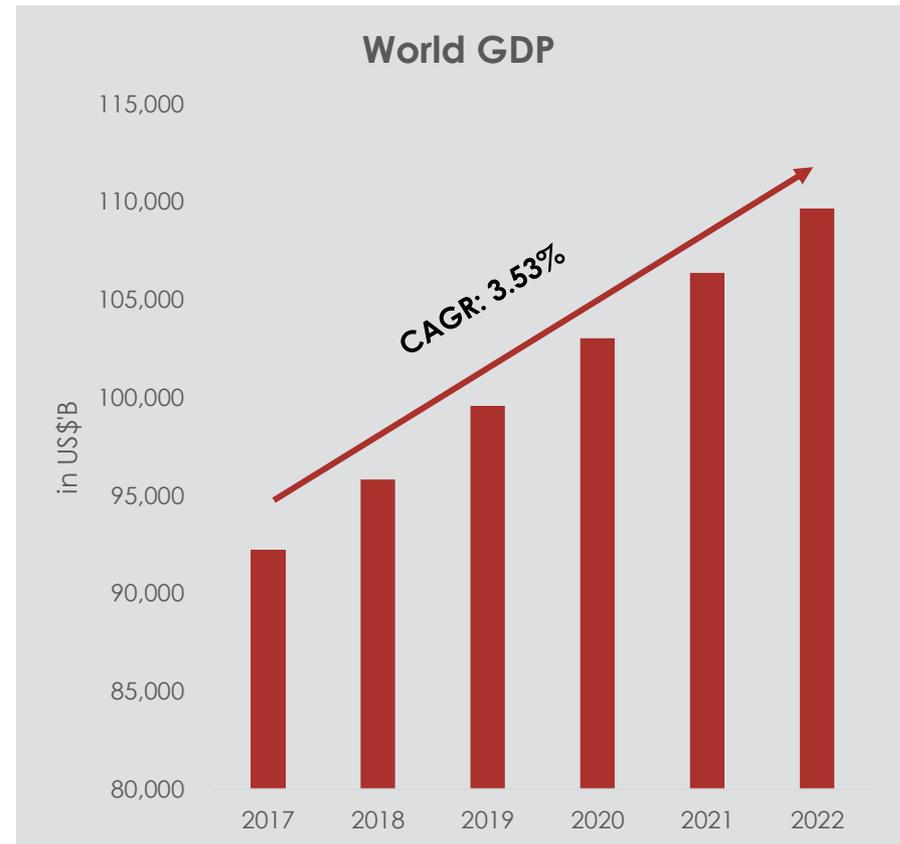
- The Group: on track to set new booking and billing records for full year 2018
- All 3 business segments: expected to set billing records for full year 2018
 - SMT solutions segment billing ~ US\$1 B
- Group billing: US\$ 550 ~ US\$ 620 million
 - SMT solutions segment: expected to achieve both QoQ and YoY growth
 - Back-end Equipment: sequential decline
 - Materials: sequential decline
- Group booking: double digit percentage decline from Q3 18

Economic Growth Drives Demand for Semiconductors

Semiconductor Revenue Growth Forecast 2019

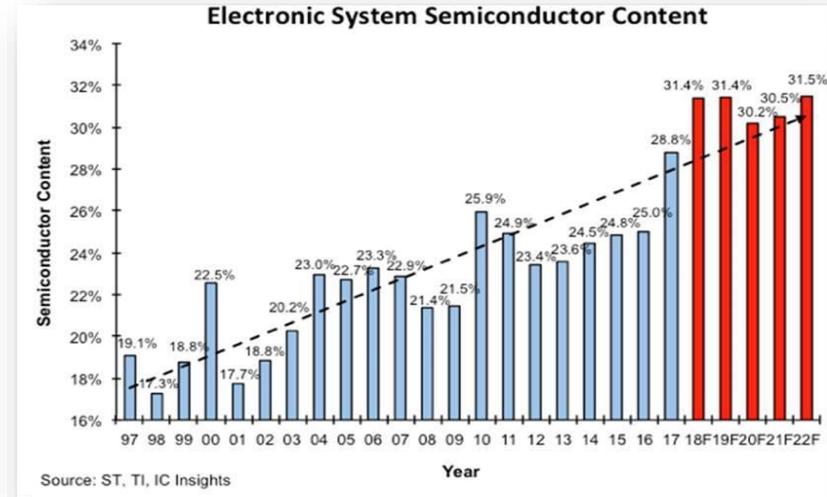
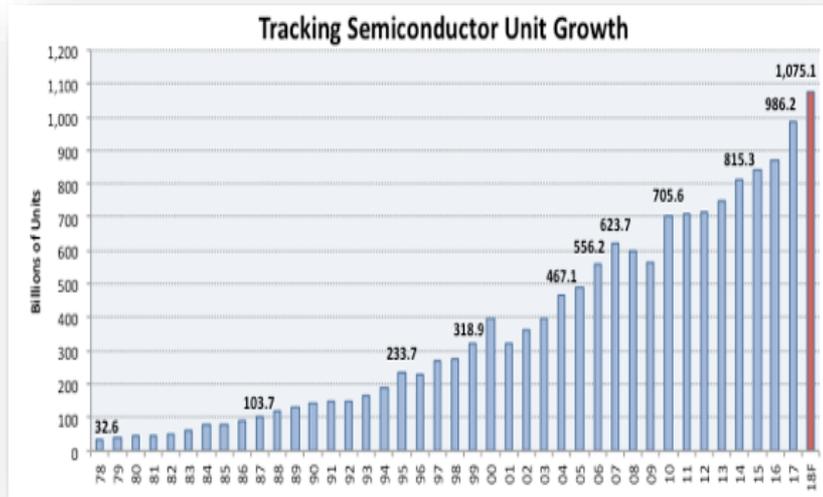


Expected Growth in Major Economies Supporting Strong Demand

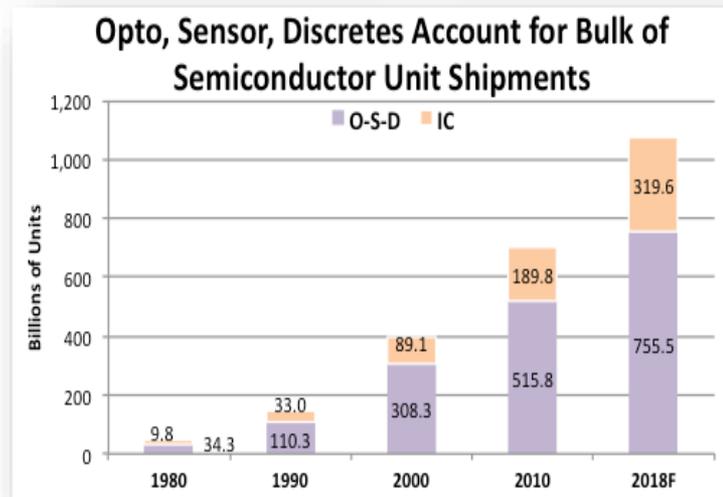


Source: OECD, Real GDP long-term forecast (indicator) Oct 18

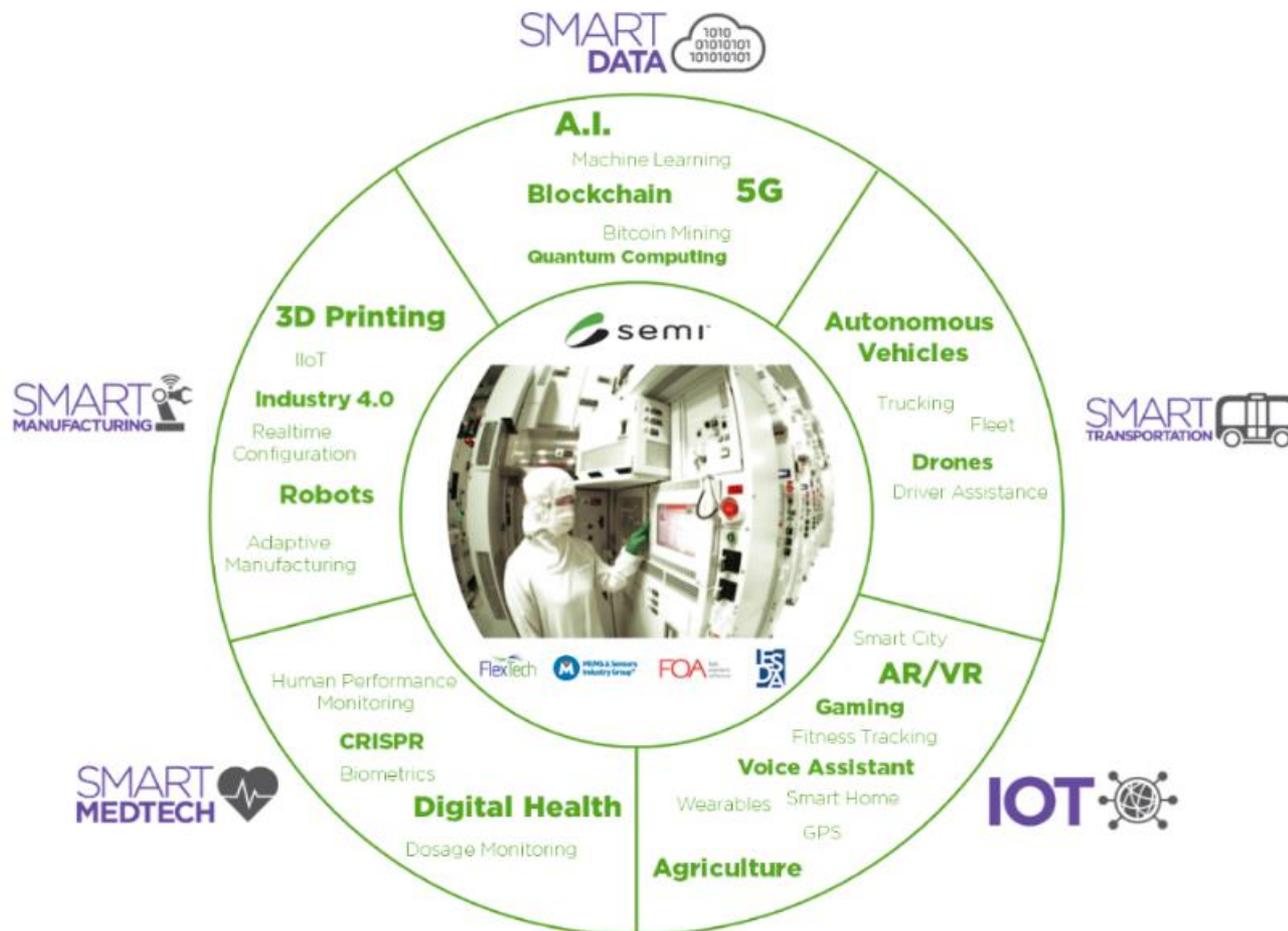
Demand for Semiconductor Devices Remains Strong



Source: IC Insights, January 2018



New Drivers in Data Centric Era Spurring Semiconductor Demands



*2017 revenue for semiconductor EDA, IP, Materials, Critical Sub-Systems, and Equipment

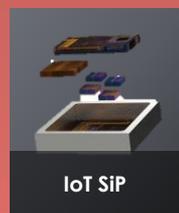
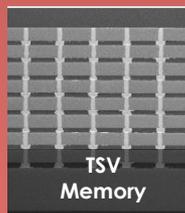
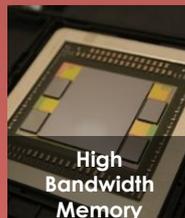
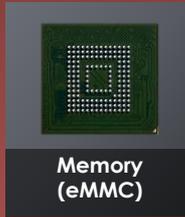
Source: SEMI, 2018

Growth Drivers



Growth Drivers – Advanced Packaging

Applications



Application Diversification Driving AP Growth

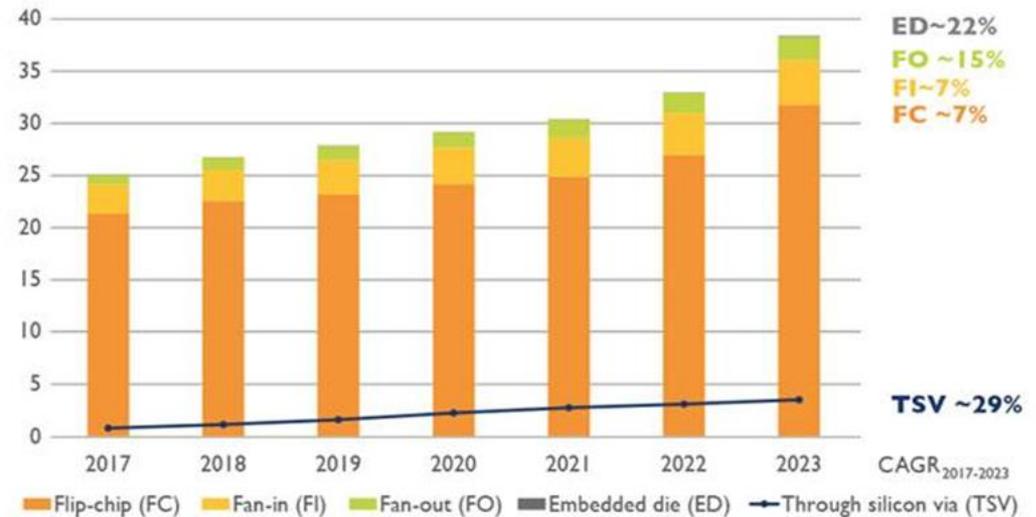
Advanced Packaging Types

CAGR (2017- 2023)

Embedded Die (ED)	~22%
Fan-out (FO)	~15%
Through Silicon Via (TSV)	~29%

2017 - 2023 advanced packaging revenue forecast, by packaging platform in \$B

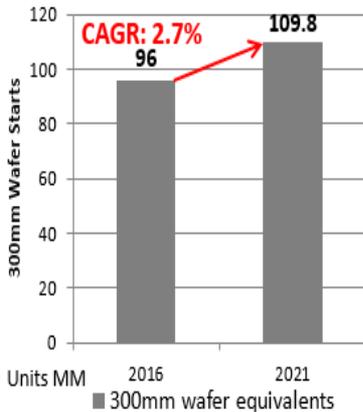
(Source: Status of the Advanced Packaging Industry 2018, Yole Développement, September 2018)



ASMPT is Covering All Interconnection Technologies

Wire Bond

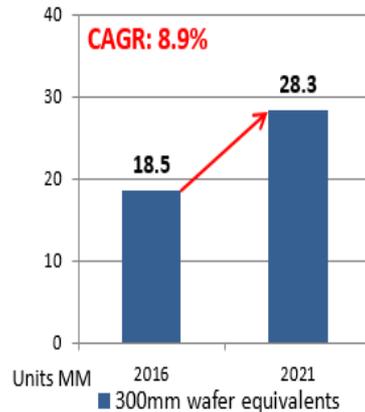
2016-2021



- Wire Bonding
- Die Bonding

Flip Chip

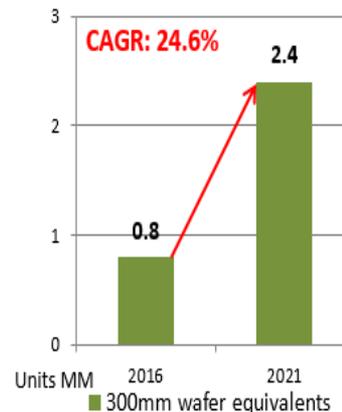
2016-2021



- Flip Chip/
NOVA Plus/
AFC Plus²
- TCB
- PVD¹
- ECD¹

Fan Out

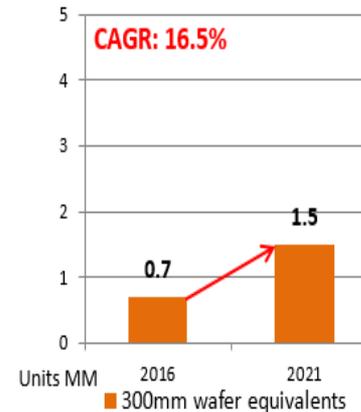
2016-2021



- NUCLEUS/ NOVA
Plus Fan Out²
- ORCAS
- SUNBIRD
- Laser
- CA
- PVD¹
- ECD¹

3D TSV

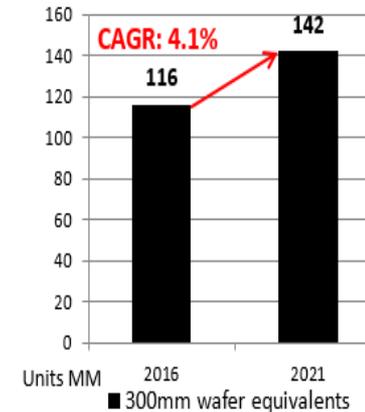
2016-2021



- TCB
- Laser
- PVD¹
- ECD¹

Total Semi. Wafers

2016-2021

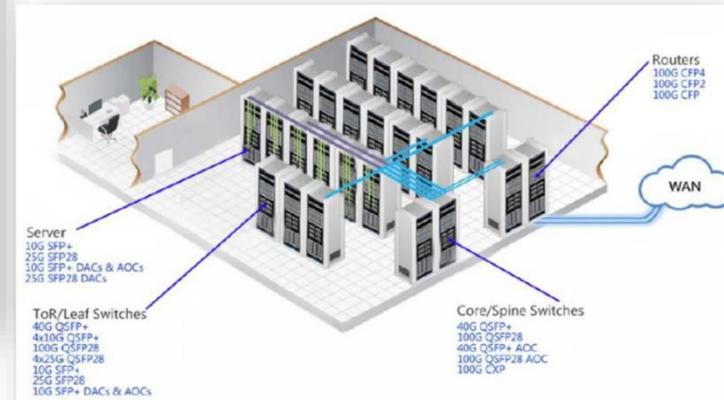
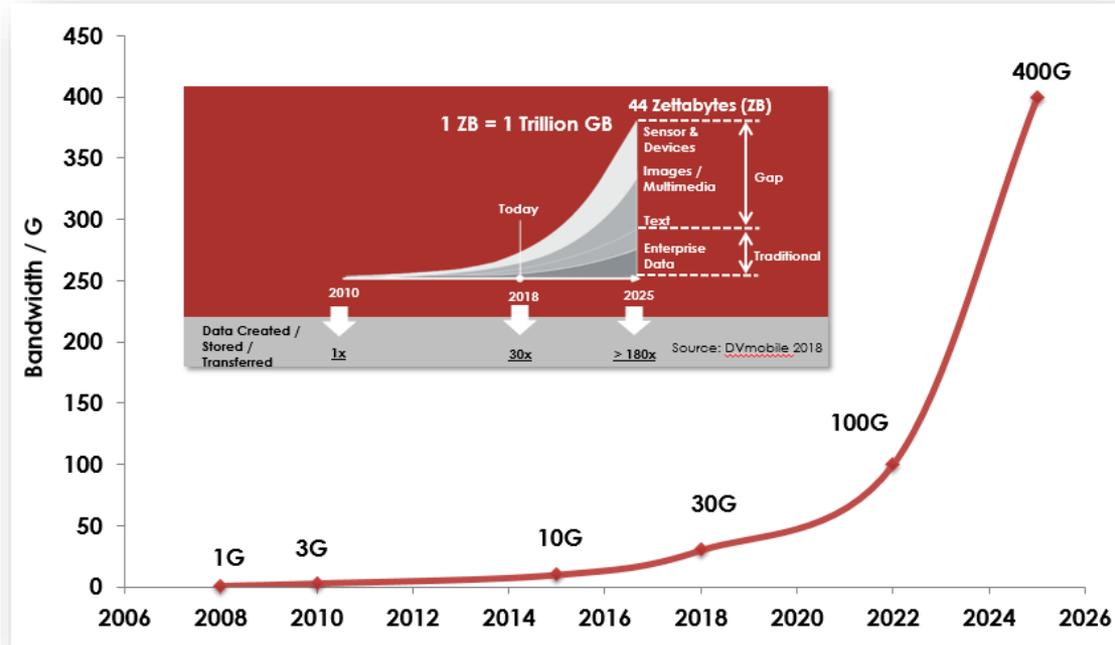


Source: Prismark Wafer Starts, 2017

¹ NEXX Product
² AMICRA Product

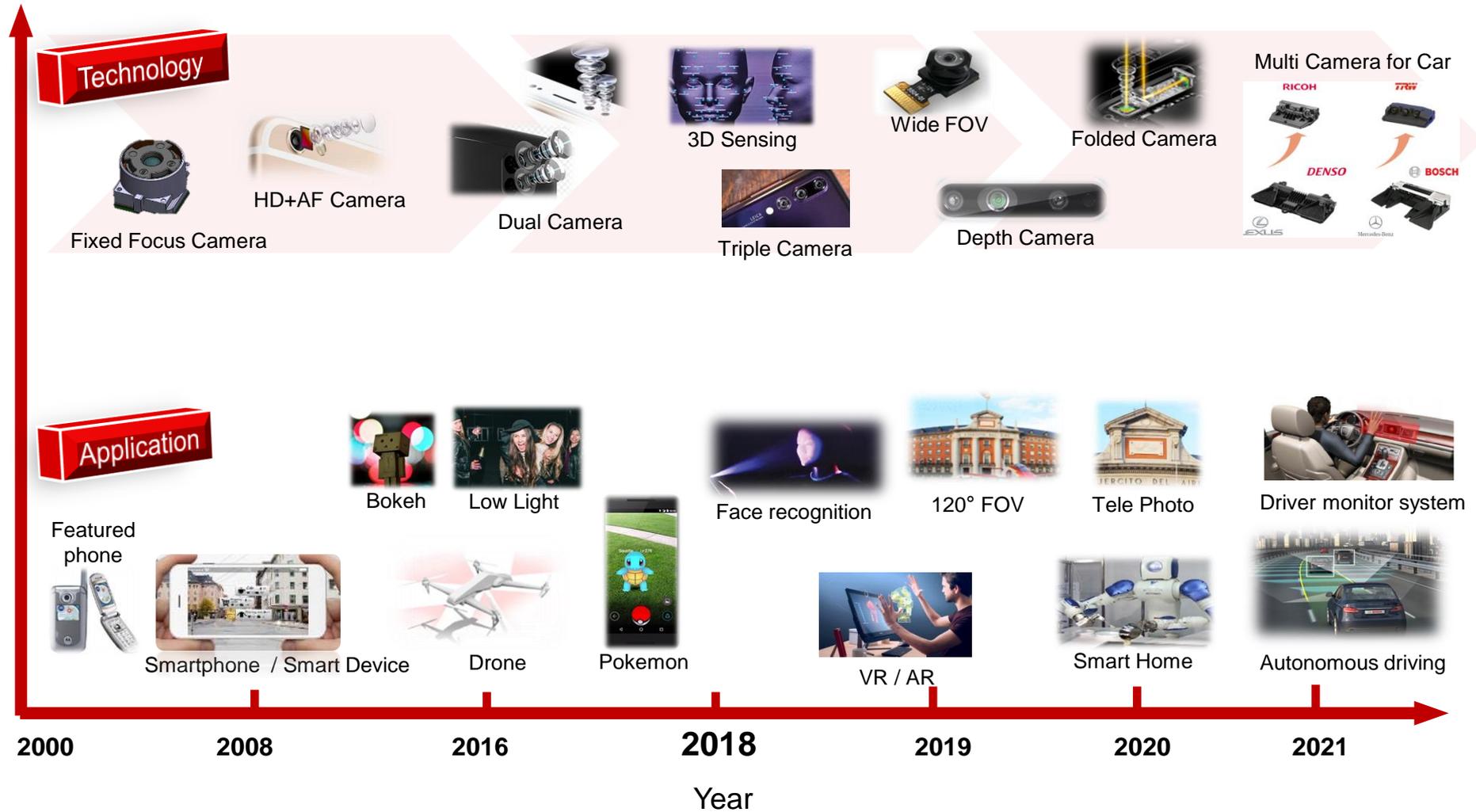
Growth Drivers – Data Centres

Si-Photonics is Key Enabling Technology for High Speed Data Transfer within and between Data Centres



Photonics is the enabling technology for 100G / 400G data communication within data centers.

Growth Drivers – Smartphone Innovations & 5G



Growth Drivers – Mini/Micro LED Displays



**Wearables
Smartphones | Tablet
Mobile Gadget**



**Small – Mid Size
Displays Backlight
Local Dimming**



**Large Displays with
True RGB color**



**Extra Large Display
Walls with True RGB
color**



Growth Drivers – Automotive



Electronic Vehicles



Autopilot



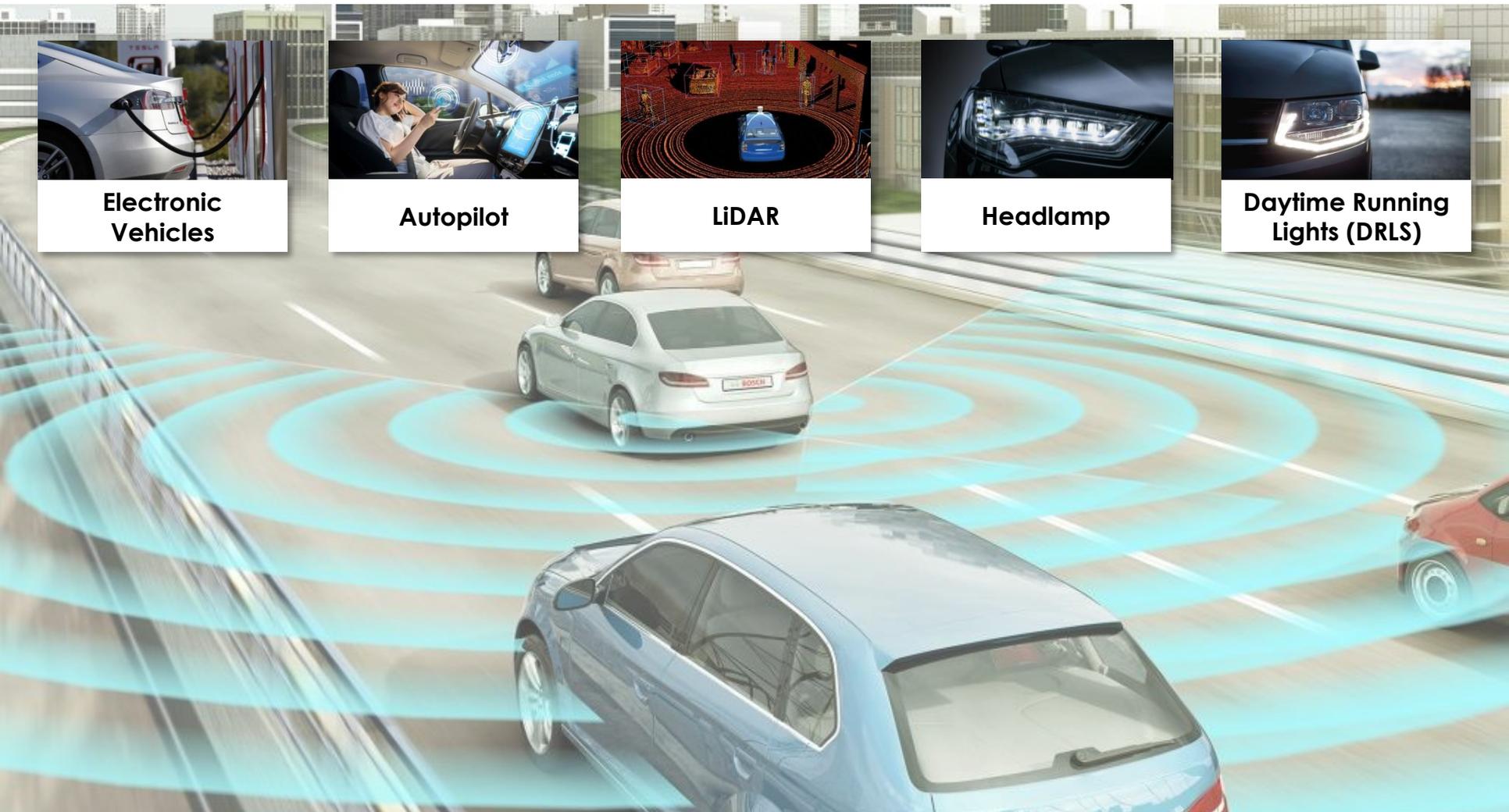
LiDAR



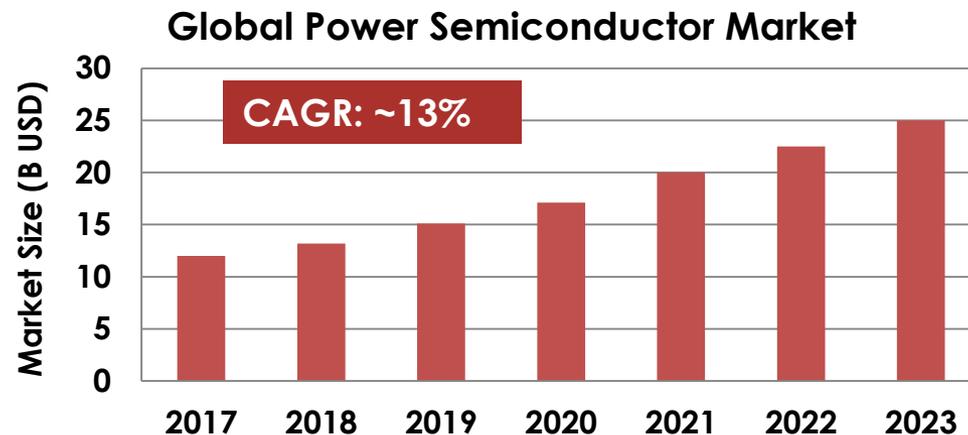
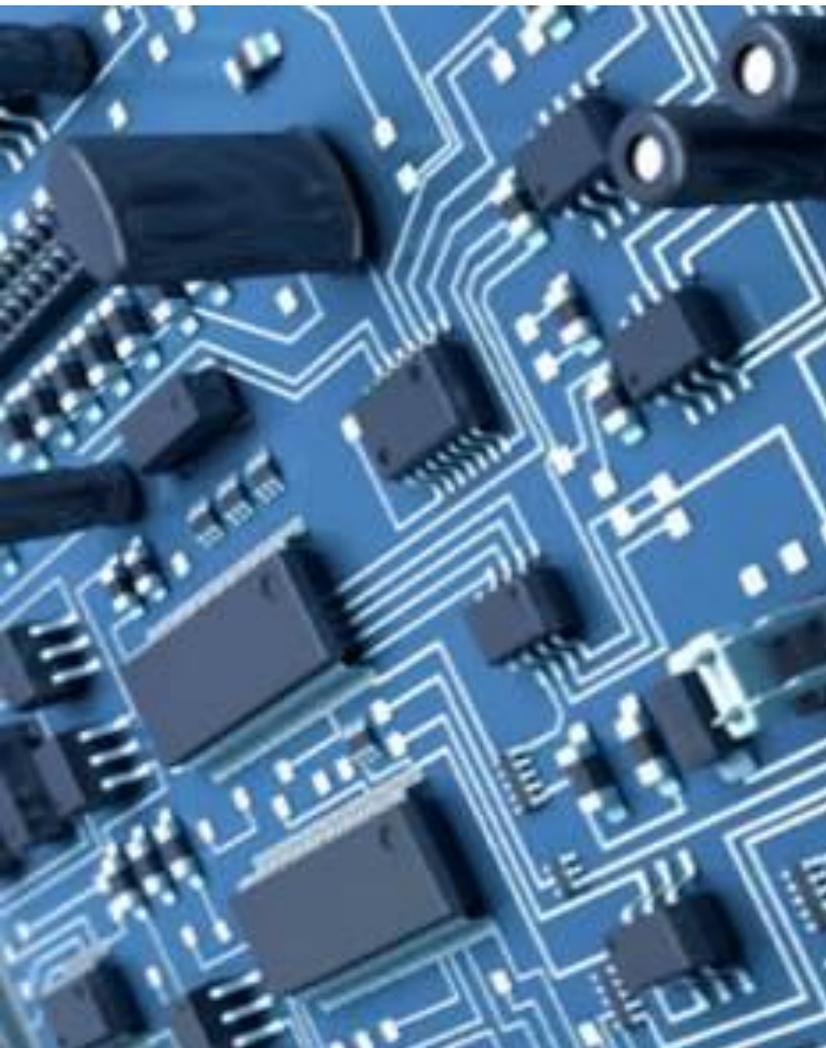
Headlamp



Daytime Running Lights (DRLS)



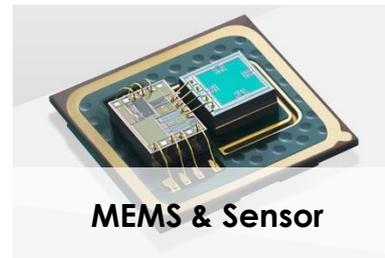
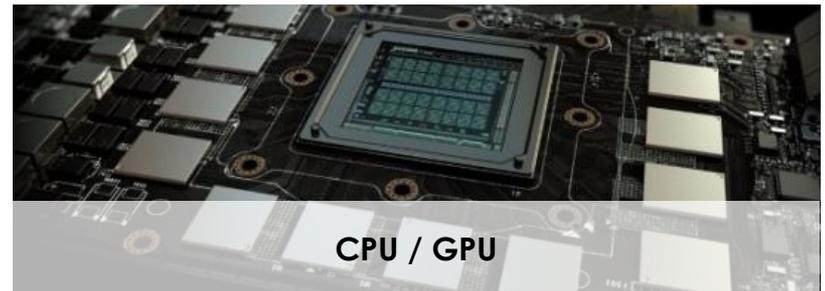
Growth Drivers – Power Management



Source: Marketresearchfuture, Oct 2018



Growth Drivers – IoT



Growth Drivers – Strategic M&A



Shareholder Value Creation

✓ Pursue Sustainable Growth & Profitability

GAIN MARKET SHARE

- ❑ Wire bonding
- ❑ Die bonding
- ❑ Lead Frames
- ❑ SMT

INVEST IN NEW GROWTH AREAS

- ❑ CMOS Image Sensor
- ❑ Automotive
- ❑ Power Management
- ❑ **Advanced Packaging**
- ❑ **Data Communication**
- ❑ **Micro / Mini LED**

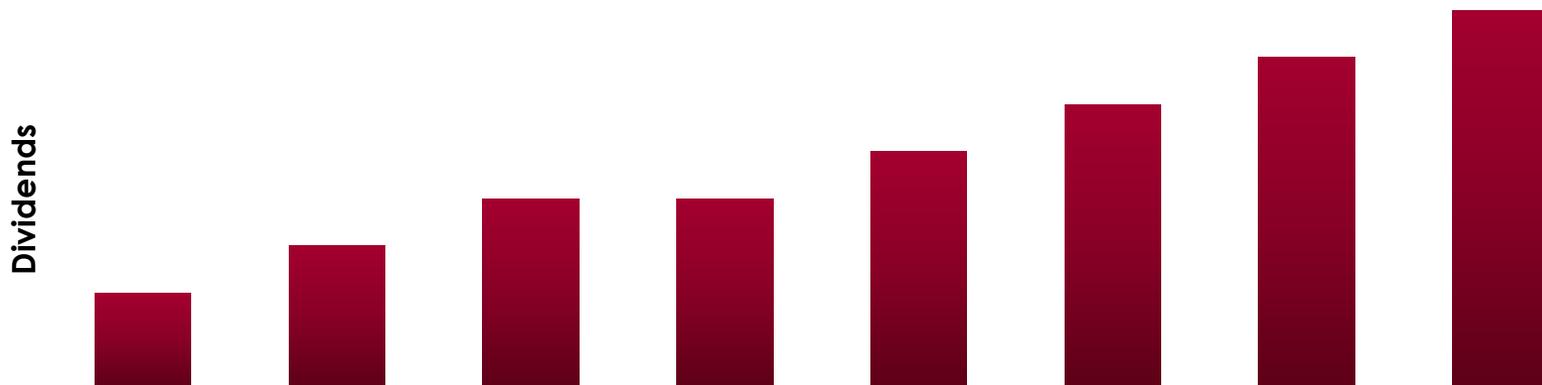
STRATEGIC M&A

- ❑ SMT Placement
- ❑ SMT Printing
- ❑ LASER Grooving / Dicing
- ❑ MIS
- ❑ **AMICRA**
- ❑ **NEXX**

Continue to Fine-Tune Organization Structure & Business Strategies

✓ Share Buyback

✓ Sustainable and Gradually Increasing Dividends



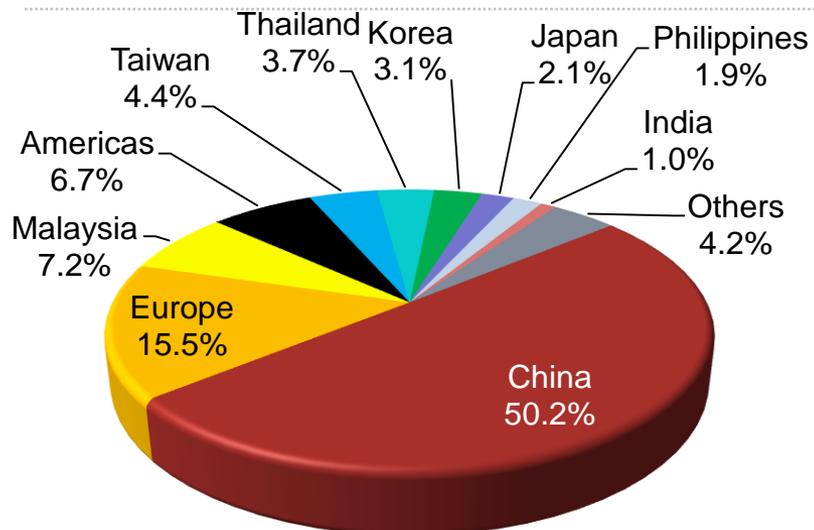
2018 Q3 FINANCIAL RESULTS



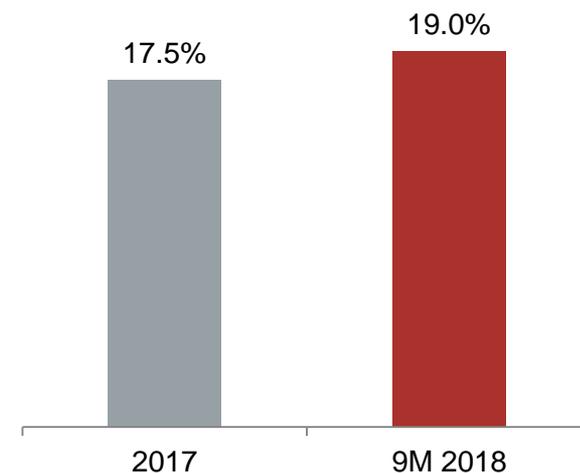
Continue To Build Business On An Extensive Customer Base

- No single customer accounted for more than 10% of the Group's revenue
- Top 5 customers collectively accounted for 19.0% of the Group's 9M 2018 sales revenue
- Top 20 customers include world's leading IDMs, Tier 1 OSAT, major OSATs in China, key LED players, major camera module makers, top EMS providers, and leading automotive component suppliers
- Among the top 20 customers of the Group, 7 were from SMT Solutions segment, and 4 were key customers from both Back-end business and SMT Solutions segment

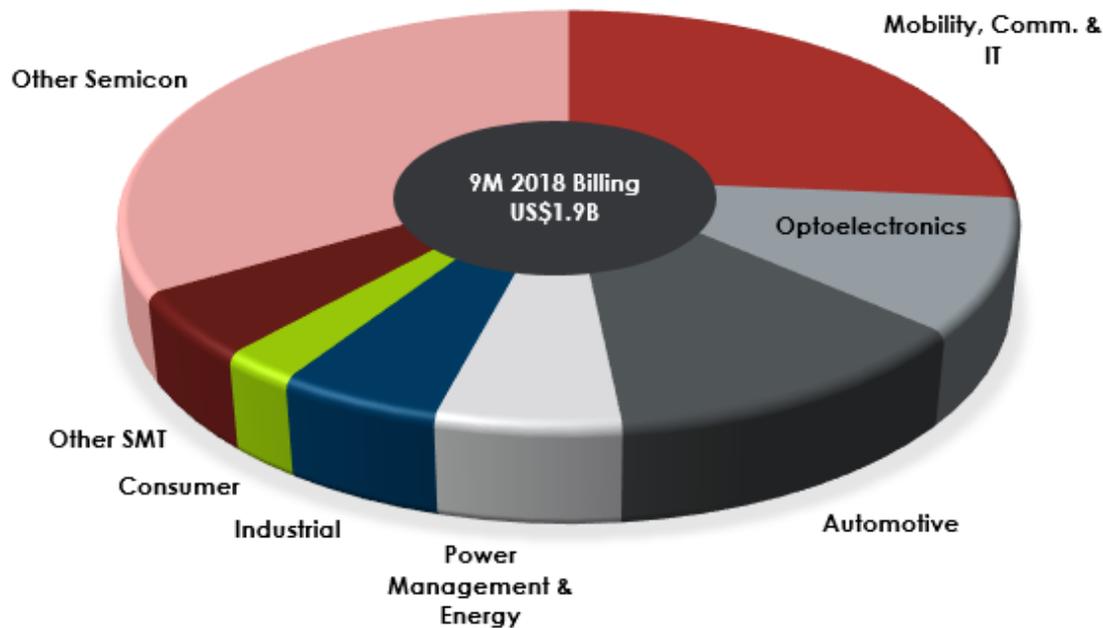
9M 2018 Geographical Distribution of Revenue



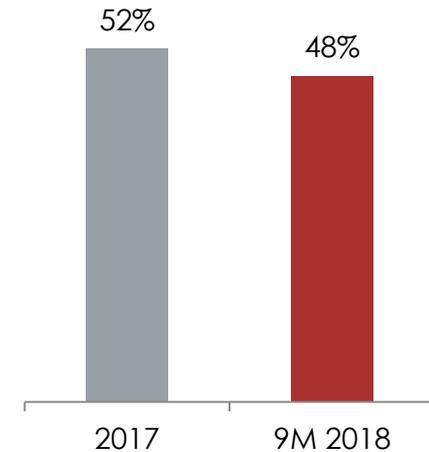
9M 2018 Revenue Contribution from Top 5 Customers



ASMPT Revenue Breakdown by Application Markets (9M 2018)



Mobility, Comm & IT, Optoelectronics and Automotive % of Group Revenue



Q3/9M 2018 Group Financial Highlights

	Q3 2018		9M 2018	
	Amount	YoY	Amount	YoY
Bookings (USD)	618.6m 	 7.7%	2.1b 	 13.9%
Billings (USD)	658.3m 	 1.1%	1.9b 	 11.2%
Gross Margin	37.8%	 283bps	39.7%	 88bps
EBIT (HKD)	818.8m	 25.3%	2.7b	 2.7% [^]
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Net Profit Margin	11.7%	 523bps	13.5%	 257bps [^]

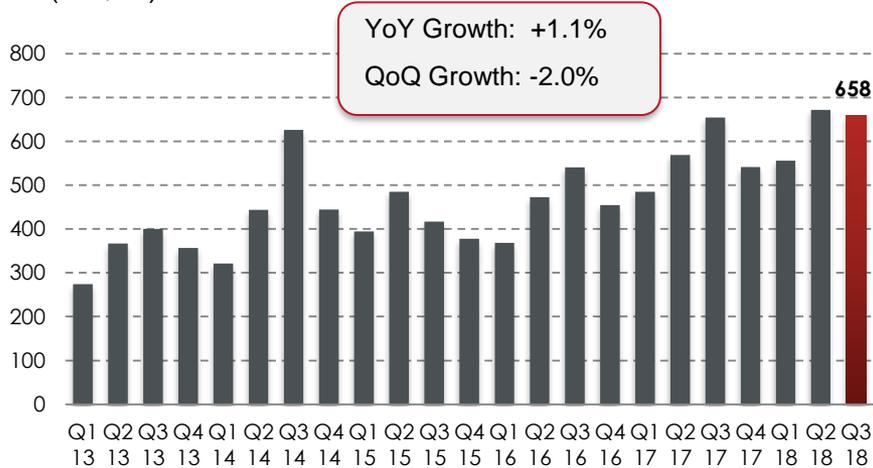
 **New Record**

 **Highest in Q3**

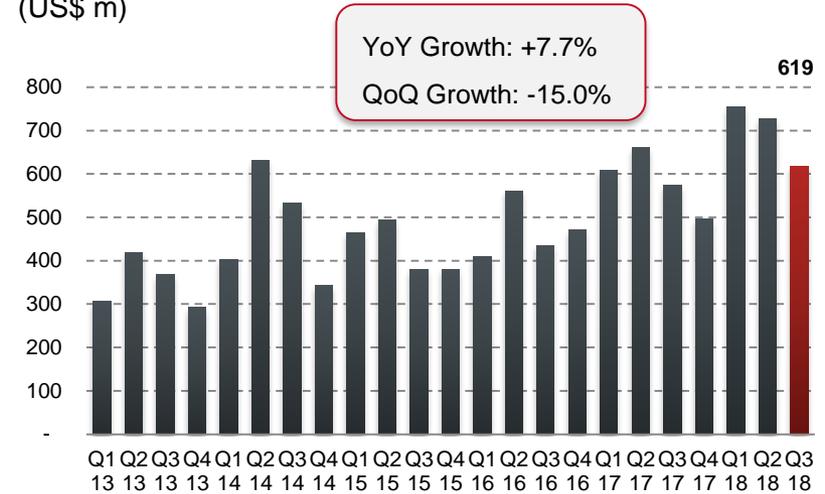
[^]Excludes adj. of liability component of CB

Q3/9M 2018 Group Highlights

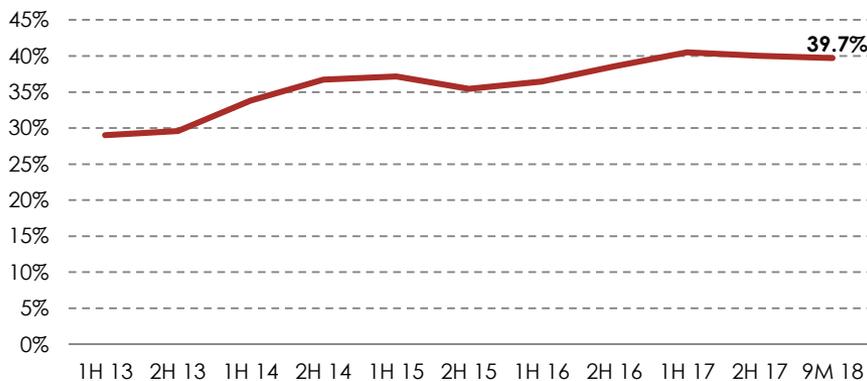
Quarterly Group Billings
(US\$ m)



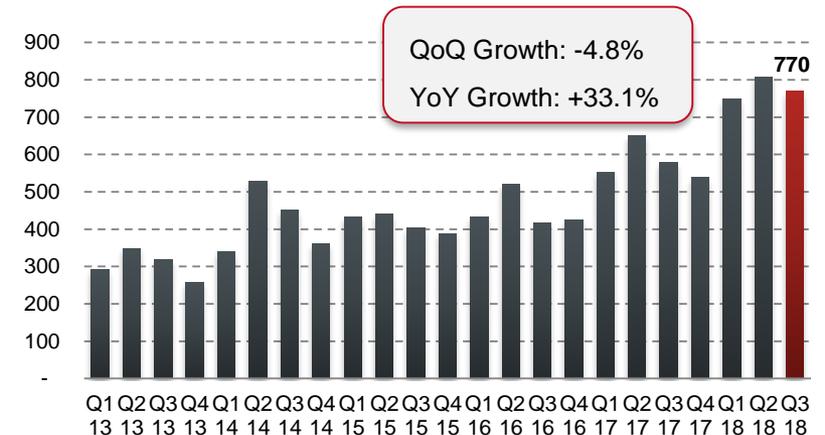
Quarterly Group Bookings
(US\$ m)



Gross Margin
(%)



Quarterly Group Backlog
(US\$ m)



Q3/9M 2018 Segment Results – Back-End Equipment Business

	Q3 2018	YoY	QoQ	9M 2018	YoY
Bookings (USD)	263.9m	↑ 5.8%	↓ 25.5%	1,024.8m	↑ 13.8%
Billings (USD)	302.6m 	↑ 5.4%	↓ 16.6%	947.9m 	↑ 11.4%
Gross Margin	43.5%	↓ 471bps	↓ 726bps	46.6%	↓ 112bps
Segment Profit (HKD)	481.8m	↓ 19.1%	↓ 44.1%	1,845.8m	↑ 5.7%
Segment Profit Margin	20.3%	↓ 616bps	↓ 999bps	24.8%	↓ 133bps

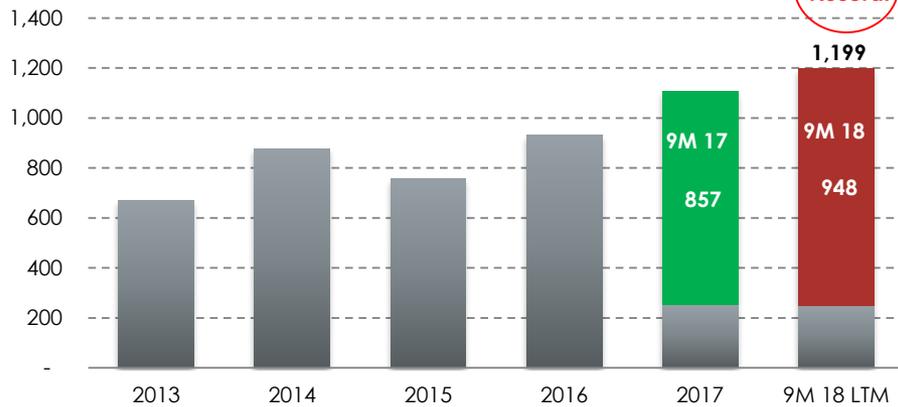
 **New Record**
 **Highest in Q3**

Q3/9M 2018 Segment Results – Back-End Equipment Business

Yearly Billings (US\$ m)

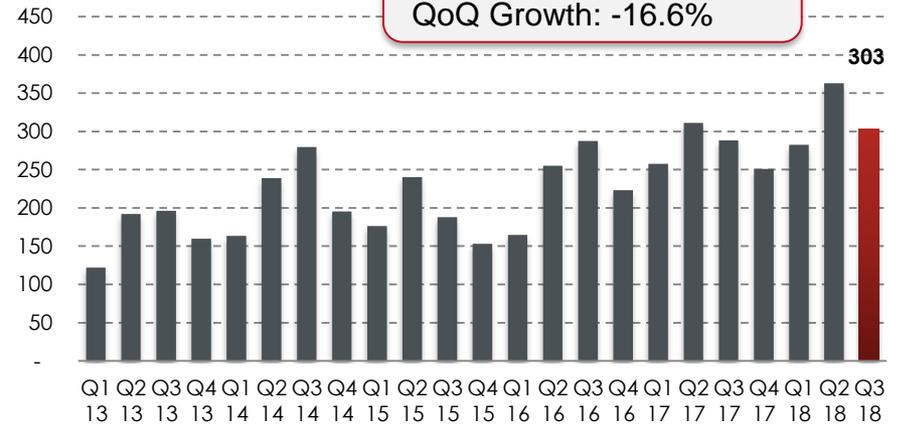
YoY Growth: +11.4%

New Record!

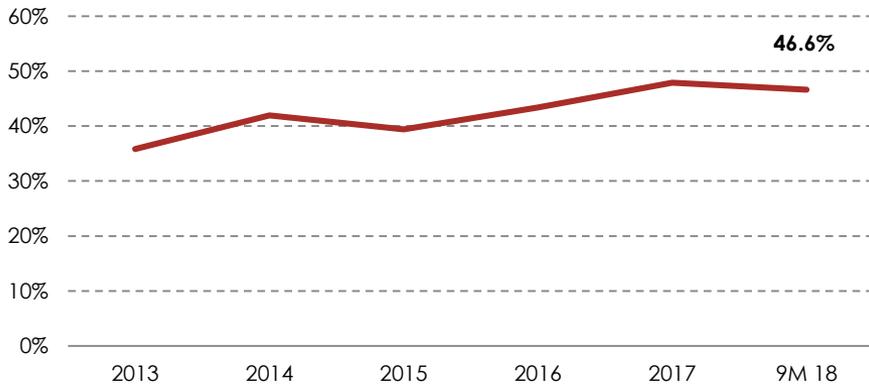


Quarterly Billings (US\$ m)

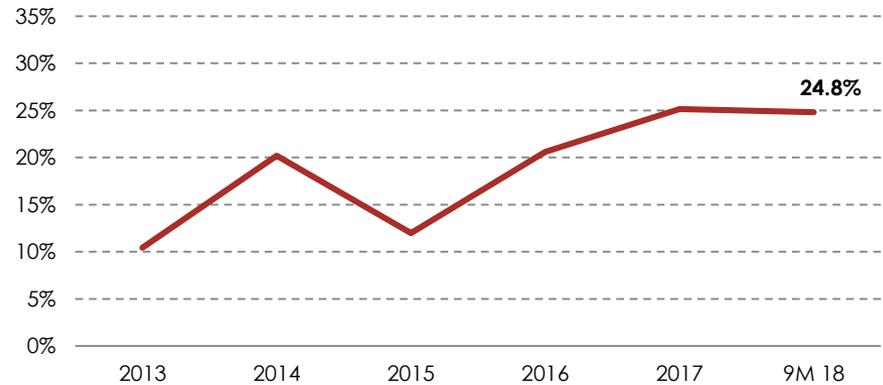
YoY Growth: +5.4%
QoQ Growth: -16.6%



Gross Margin (%)



Segment Profit Margin (%)

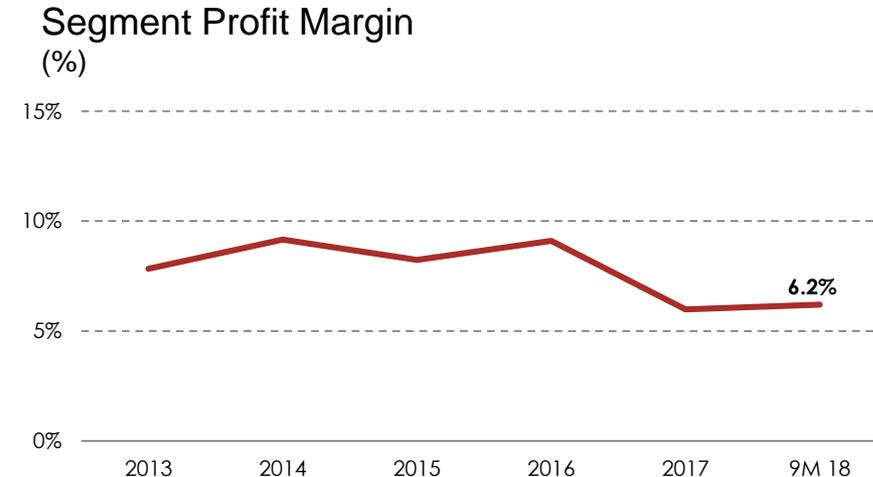
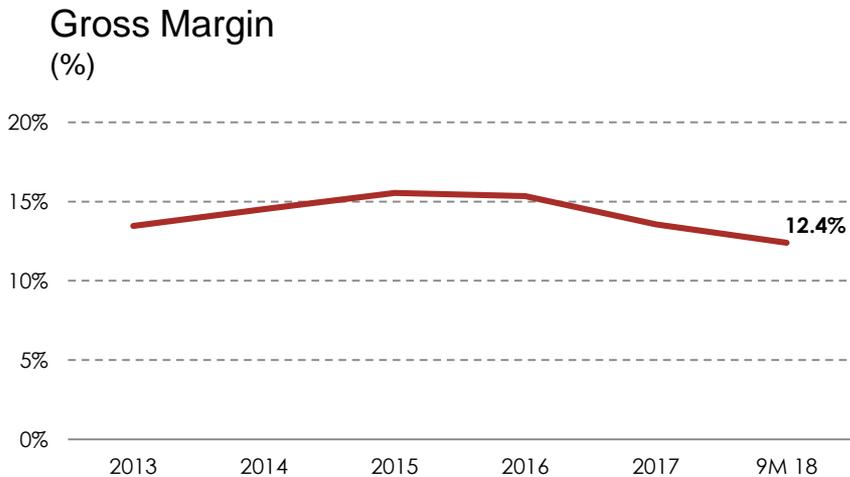
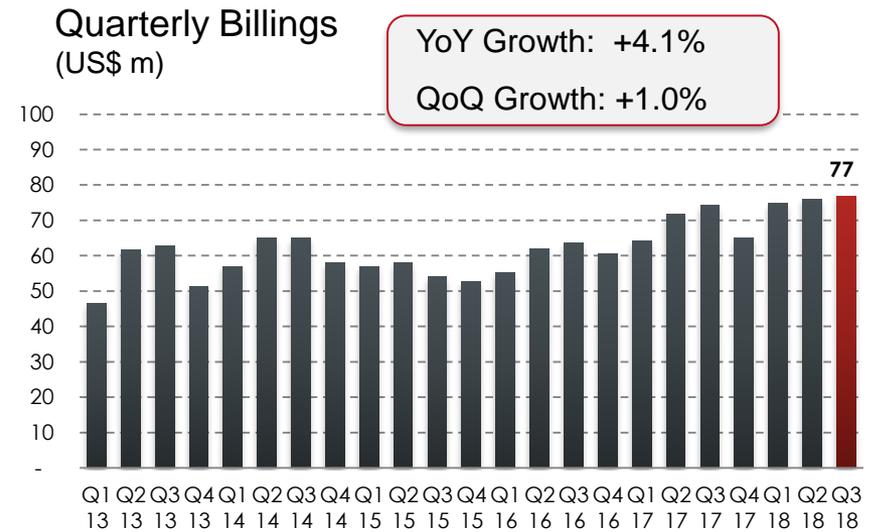
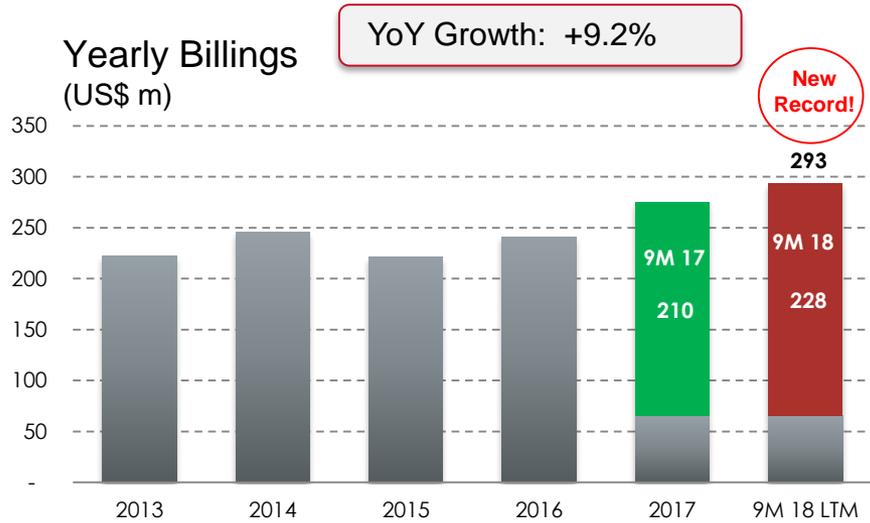


Q3/9M 2018 Segment Results – Materials Business

	Q3 2018	YoY	QoQ	9M 2018	YoY
Bookings (USD)	53.9m	↓ 20.8%	↓ 30.4%	204.9m	↓ 11.4%
Billings (USD)	76.9m [★]	↑ 4.1%	↑ 1.0%	227.9m [★]	↑ 9.2%
Gross Margin	11.0%	↓ 370bps	↓ 230bps	12.4%	↓ 152bps
Segment Profit (HKD)	26.3m	↓ 43.1%	↓ 41.4%	110.4m	↓ 8.6%
Segment Profit Margin	4.4%	↓ 362bps	↓ 315bps	6.2%	↓ 121bps

 **New Record**
 **Highest in Q3**

Q3/9M 2018 Segment Results – Materials Business



Q3/9M 2018 Segment Results – SMT Solutions Business

	Q3 2018	YoY	QoQ	9M 2018	YoY
Bookings (USD)	300.8m 	 17.1%	 1.6%	870.8m 	 22.3%
Billings (USD)	278.8m	 3.9%	 19.8%	709.8m 	 11.6%
Gross Margin	39.0%	 72bps	 228bps	39.2%	 52bps
Segment Profit (HKD)	435.7m	 13.6%	 28.3%	975.9m 	 7.9%
Segment Profit Margin	19.9%	 224bps	 132bps	17.5%	 59bps

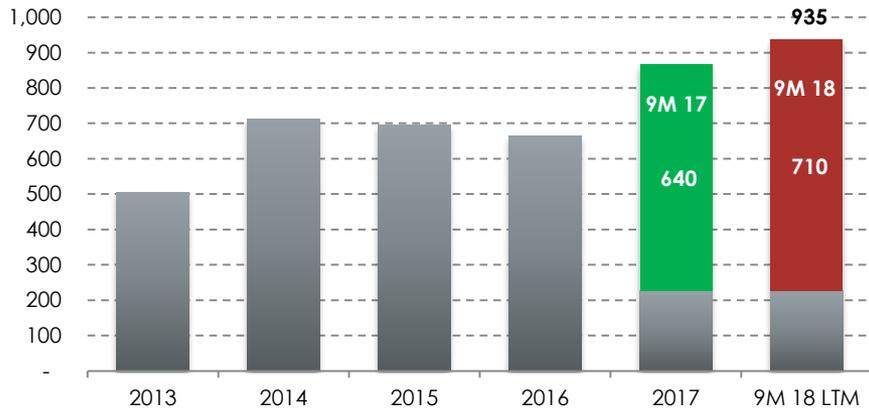
 **New Record**

Q3/9M 2018 Segment Results – SMT Solutions Business

Yearly Billings
(US\$ m)

YoY Growth: +11.6%

New Record!



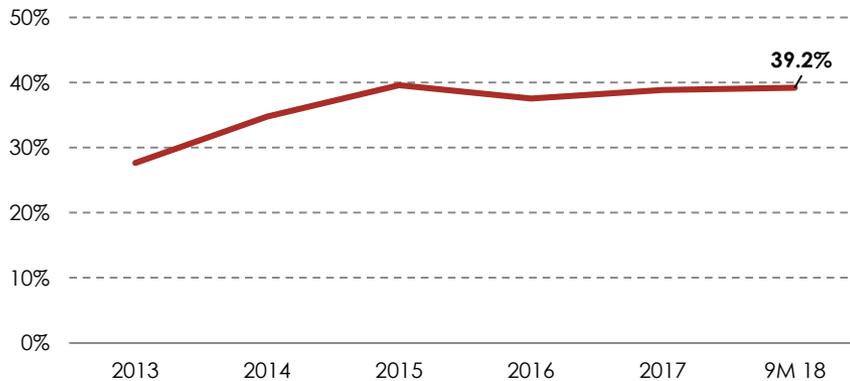
Quarterly Billings
(US\$ m)

YoY Growth: -3.9%

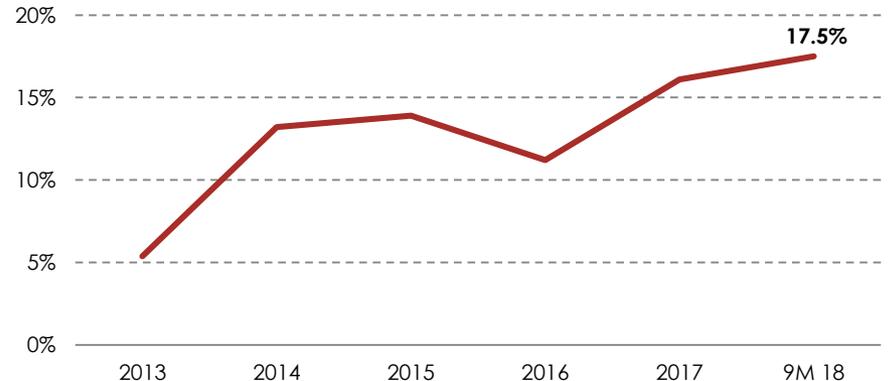
QoQ Growth: +19.8%



Gross Margin
(%)



Segment Profit Margin
(%)



AWARDS & RECOGNITION



Recent Awards & Recognition

- Technology Achievement Grand Award of HKIA 2017
(for the third time)
Federation of HK Industries



- Directors of the Year Awards 2017
Hong Kong Institute of Directors



- Hong Kong Outstanding Enterprises 2017
HK Economic Digest



- 2017 All Stars of the Semiconductor Industry
VLSI Research

VLSIresearch's 2017 All Stars

Recent Awards & Recognition

- Factory of the Year 2016 Award (for SMT) by Produktion/AT Kearney



- Ranked among Top 10 of Best Managed HK Companies
- Ranked among Top 10 of Best at Investor Relations



- 2017 & 2018 “Triple Crown” with RANKED 1st/10 BEST/BEST Suppliers Awards from VLSIresearch



- 2016-17 Corporate Governance Asia – Best Investor Relations Company (HK)
- 2017 Corporate Governance Asia – Best CEO (Investor Relations)



- 2015 Hong Kong Awards for Industries: Technology Achievement Grand Award



VLSI Awards 2018

				
10 BEST Segment	Rank	10 BEST CHIP MAKING EQUIPMENT SUPPLIERS OF 2018	Rating	Stars
L A R G E	1	TERADYNE	9.25	★★★★★
	2	ADVANTEST	9.10	★★★★★
	3	ASML	9.05	★★★★★
	4	Hitachi Kokusai Electric	8.90	★★★★★
	5	TEL TOKYO ELECTRON	8.45	★★★★
	6	APPLIED MATERIALS	7.55	★★★★☆
	7	ASM Pacific Technology	7.45	★★★
	8	Hitachi High-Tech	7.45	★★★
F O C U S E D	1	Plasma-Therm	9.01	★★★★★
	2	AMEC	8.95	★★★★★
	3	FORMFACTOR	8.94	★★★★★
	4	SPTS	8.90	★★★★★
	5	Xcerra Advanced by your system	8.76	★★★★★
	6	EVG	8.42	★★★★
	7	ACCRETECH TOKYO SEIMITSU	7.22	★★★

			WHAT THE BEST SUPPLIERS OF 2018 ARE BEST AT
ACCRETECH TOKYO SEIMITSU	<ul style="list-style-type: none"> Uptime Usable Performance 	<ul style="list-style-type: none"> Trust in Supplier Recommend Supplier 	
AMEC	<ul style="list-style-type: none"> Recommend Supplier Trust in Supplier 	<ul style="list-style-type: none"> Field Engineering Support Uptime 	
ASM Pacific Technology	<ul style="list-style-type: none"> Field Engineering Support Support After Sales 	<ul style="list-style-type: none"> Recommend Supplier Technical Leadership 	
EVG	<ul style="list-style-type: none"> Technical Leadership Trust in Supplier 	<ul style="list-style-type: none"> Technical Leadership Recommend Supplier 	
Hitachi High-Tech	<ul style="list-style-type: none"> Trust in Supplier Uptime 	<ul style="list-style-type: none"> Field Engineering Support Process Support 	
JAPAN ELECTRONIC MATERIALS	<ul style="list-style-type: none"> Partnering Recommend Supplier 	<ul style="list-style-type: none"> Partnering Commitment 	
Plasma-Therm	<ul style="list-style-type: none"> Trust in Supplier Spares Support 	<ul style="list-style-type: none"> Recommend Supplier Uptime 	
TECHNOPROBE Wafer Probing Technology	<ul style="list-style-type: none"> Support After Sales Trust in Supplier and Partnering 	<ul style="list-style-type: none"> Trust in Supplier Recommend Supplier 	
TEL TOKYO ELECTRON	<ul style="list-style-type: none"> Trust in Supplier Uptime 	<ul style="list-style-type: none"> Trust in Supplier Recommend Supplier 	

			RATINGS FOR THE BEST SUPPLIERS OF 2018
	ASSEMBLY EQUIPMENT	Rating	VLSI STARS
1	ASM Pacific Technology	7.47	★★★

